



(51) International Patent Classification:

H01L 21/67 (2006.01) *B65G 49/07* (2006.01)
H01L 21/683 (2006.01) *B25B 11/00* (2006.01)

(21) International Application Number:

PCT/SG2013/000269

(22) International Filing Date:

28 June 2013 (28.06.2013)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

61/667,659 3 July 2012 (03.07.2012) US

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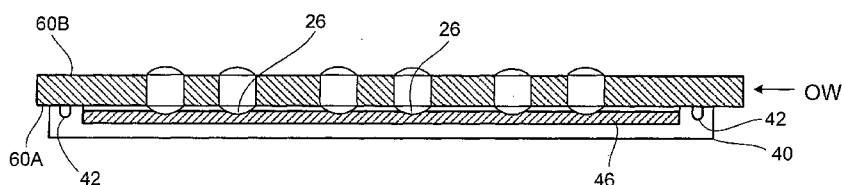
(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))

(54) Title: USE OF VACUUM CHUCKS TO HOLD A WAFER OR WAFER SUB-STACK



(57) Abstract: Techniques are described for holding a wafer or wafer sub-stack to facilitate further processing of the wafer or sub-stack. In some implementations, a wafer or wafer sub-stack is held by a vacuum chuck in a manner that can help reduce bending of the wafer or wafer sub-stack.